

**IGBT** 

# SGH10N60RUFD

# Short Circuit Rated IGBT

# **General Description**

Fairchild's RUFD series of Insulated Gate Bipolar Transistors (IGBTs) provide low conduction and switching losses as well as short circuit ruggedness. The RUFD series is designed for applications such as motor control, uninterrupted power supplies (UPS) and general inverters where short circuit ruggedness is a required feature.

#### **Features**

- Short circuit rated 10us @  $T_C = 100$ °C,  $V_{GE} = 15$ V
- High speed switching
- Low saturation voltage :  $V_{CE(sat)} = 2.2 \text{ V} @ I_C = 10 \text{A}$
- · High input impedance
- CO-PAK, IGBT with FRD :  $t_{rr} = 42$ ns (typ.)

# **Applications**

AC & DC motor controls, general purpose inverters, robotics, and servo controls.





# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Description		SGH10N60RUFD	Units	
V <sub>CES</sub>	Collector-Emitter Voltage		600	V	
V <sub>GES</sub>	Gate-Emitter Voltage		± 20	V	
_	Collector Current	@ $T_C = 25^{\circ}C$	16	Α	
IC	Collector Current	@ T <sub>C</sub> = 100°C	10	Α	
I <sub>CM (1)</sub>	Pulsed Collector Current		30	Α	
I <sub>F</sub>	Diode Continuous Forward Current	@ T <sub>C</sub> = 100°C	12	Α	
I <sub>FM</sub>	Diode Maximum Forward Current		92	Α	
T <sub>SC</sub>	Short Circuit Withstand Time	@ T <sub>C</sub> = 100°C	10	us	
$P_{D}$	Maximum Power Dissipation	@ T <sub>C</sub> = 25°C	75	W	
	Maximum Power Dissipation	@ T <sub>C</sub> = 100°C	30	W	
T <sub>J</sub>	Operating Junction Temperature		-55 to +150	°C	
T <sub>stg</sub>	Storage Temperature Range		-55 to +150	°C	
T <sub>L</sub>	Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 Secon	ds	300	°C	

#### Notes :

(1) Repetitive rating : Pulse width limited by max. junction temperature

## Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction-to-Case		1.6	°C/W
$R_{\theta JC}(DIODE)$	Thermal Resistance, Junction-to-Case		2.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chai	racteristics					
BV <sub>CES</sub>	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250uA$	600			V
$\Delta B_{VCES}/$ $\Delta T_J$	Temperature Coefficient of Breakdown Voltage	$V_{GE} = 0V$ , $I_C = 1mA$		0.6		V/°C
I <sub>CES</sub>	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			250	uA
I <sub>GES</sub>	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
On Char	acteristics					
V <sub>GE(th)</sub>	G-E Threshold Voltage	$I_C = 10$ mA, $V_{CE} = V_{GE}$	5.0	6.0	8.5	V
	Collector to Emitter	$I_C = 10A$ , $V_{GE} = 15V$		2.2	2.8	V
V <sub>CE(sat)</sub>	Saturation Voltage	$I_C = 16A$ , $V_{GE} = 15V$		2.5		V
Dynami	Characteristics					
C <sub>ies</sub>	Input Capacitance			660		pF
C <sub>oes</sub>	Output Capacitance	$V_{CE} = 30V, V_{GE} = 0V,$		115		pF
C <sub>res</sub>	Reverse Transfer Capacitance	f = 1MHz		25		pF
. ` ′	,	-				ns
t <sub>d(on)</sub>	Turn-On Delay Time			15		ns
t <sub>r</sub>	Rise Time			30		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 10\text{A},$		36	50	ns
t <sub>f</sub>	Fall Time	$R_G = 20\Omega, V_{GE} = 15V,$		158	200	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 25°C		141		uJ
E <sub>off</sub>	Turn-Off Switching Loss			215		uJ
E <sub>ts</sub>	Total Switching Loss			356	500	uJ
t <sub>d(on)</sub>	Turn-On Delay Time			16		ns
t <sub>r</sub>	Rise Time			33		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 10 \text{A},$		42	60	ns
t <sub>f</sub>	Fall Time	$R_G = 20\Omega$ , $V_{GE} = 15V$ ,		242	350	ns
E <sub>on</sub>	Turn-On Switching Loss	Inductive Load, T <sub>C</sub> = 125°C		161		uJ
E <sub>off</sub>	Turn-Off Switching Loss			452		uJ
E <sub>ts</sub>	Total Switching Loss	1		613	860	uJ
T <sub>sc</sub>	Short Circuit Withstand Time	V <sub>CC</sub> = 300 V, V <sub>GE</sub> = 15V @ T <sub>C</sub> = 100°C	10			us
Qg	Total Gate Charge			30	45	nC
Q <sub>ge</sub>	Gate-Emitter Charge	$V_{CE} = 300 \text{ V}, I_{C} = 10\text{A},$		5	10	nC
Q <sub>gc</sub>	Gate-Collector Charge	V <sub>GE</sub> = 15V		8	16	nC
		T. Control of the Con	1		1	

# Electrical Characteristics of DIODE $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
\/	Diode Forward Voltage	I <sub>F</sub> = 12A	$T_C = 25^{\circ}C$		1.4	1.7	V
$V_{FM}$	Didde Forward Voltage	1 <sub>F</sub> = 12A	T <sub>C</sub> = 100°C		1.3		V
t <sub>rr</sub>	Diode Reverse Recovery Time		$T_C = 25^{\circ}C$		42	60	ns
			T <sub>C</sub> = 100°C		60		
1	Diode Peak Reverse Recovery	I <sub>F</sub> = 12A, di/dt = 200A/us	$T_C = 25^{\circ}C$		3.5	6.0	Α
¹rr	<sup>I</sup> rr Current		T <sub>C</sub> = 100°C		5.6		_ ^
Q <sub>rr</sub>	Diode Reverse Recovery Charge		$T_C = 25^{\circ}C$		80	180	nC
			T <sub>C</sub> = 100°C		220		110

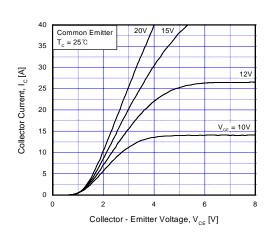
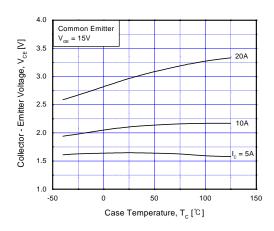


Fig 1. Typical Output Characteristics

Fig 2. Typical Saturation Voltage Characteristics



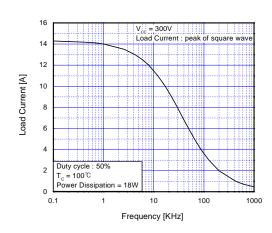
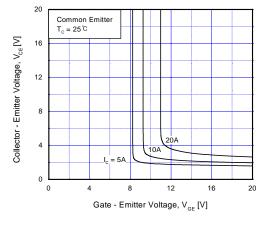


Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level

Fig 4. Load Current vs. Frequency



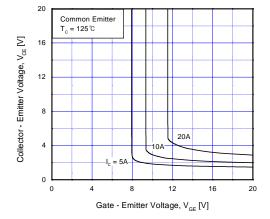


Fig 5. Saturation Voltage vs.  $V_{GE}$ 

Fig 6. Saturation Voltage vs.  $V_{\rm GE}$ 

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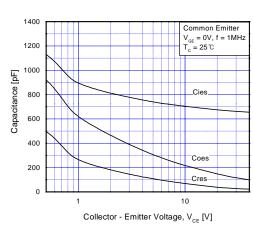


Fig 7. Capacitance Characteristics

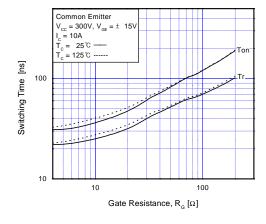


Fig 8. Turn-On Characteristics vs.
Gate Resistance

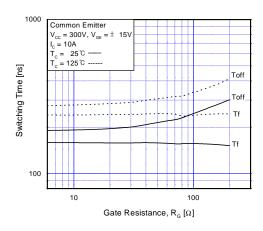


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

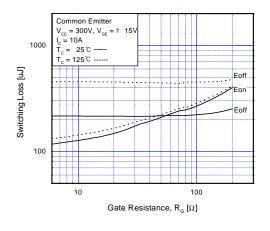


Fig 10. Switching Loss vs. Gate Resistance

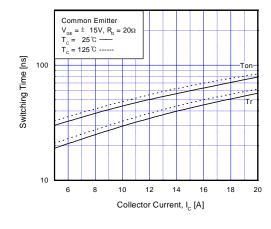


Fig 11. Turn-On Characteristics vs. Collector Current

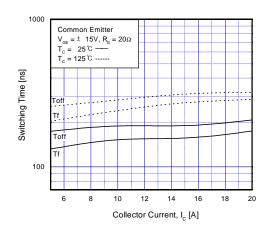
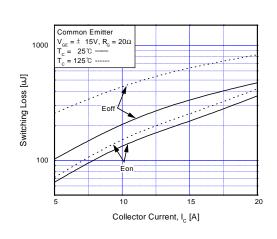


Fig 12. Turn-Off Characteristics vs. Collector Current



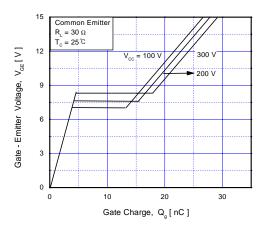
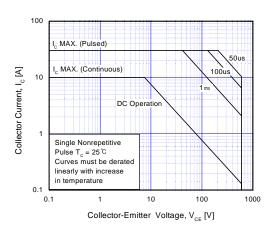


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



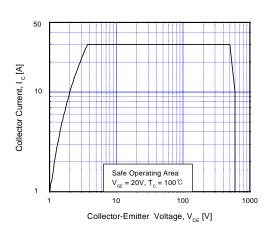


Fig 15. SOA Characteristics

Fig 16. Turn-Off SOA Characteristics

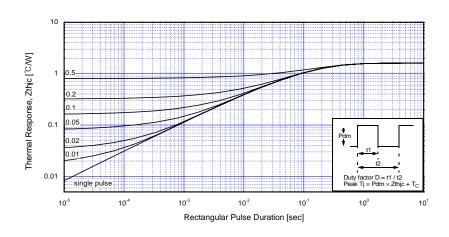
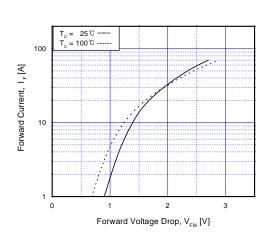


Fig 17. Transient Thermal Impedance of IGBT



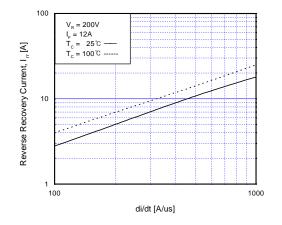
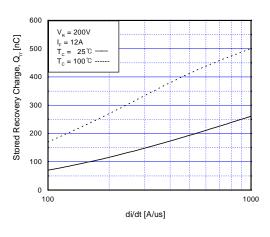


Fig 18. Forward Characteristics

Fig 19. Reverse Recovery Current



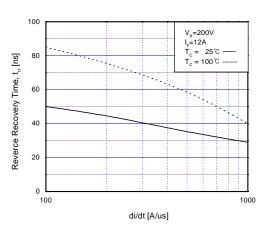
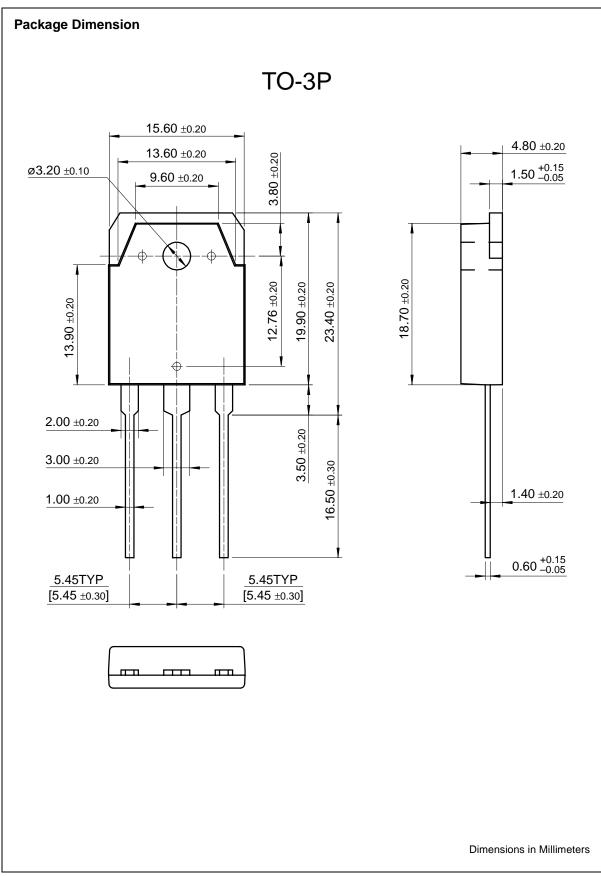


Fig 20. Stored Charge

Fig 21. Reverse Recovery Time



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# back to top

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Product	<b>Product status</b>	Pricing*	Package type	Leads	Packing method
SGH10N60RUFDTU	Full Production	\$2.21	TO-3P	3	RAIL

<sup>\* 1,000</sup> piece Budgetary Pricing

# back to top

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